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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	16
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	384 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1827-e-ss

TABLE 1-2: PIC16(L)F1826/27 PINOUT DESCRIPTION

Name	Function	Input Type	Output Type	Description
RA0/AN0/CPS0/C12IN0-/ SDO2(2)	RA0	TTL	CMOS	General purpose I/O.
	AN0	AN	—	A/D Channel 0 input.
	CPS0	AN	—	Capacitive sensing input 0.
	C12IN0-	AN	—	Comparator C1 or C2 negative input.
	SDO2	—	CMOS	SPI data output.
RA1/AN1/CPS1/C12IN1-/$\overline{SS2}$(2)	RA1	TTL	CMOS	General purpose I/O.
	AN1	AN	—	A/D Channel 1 input.
	CPS1	AN	—	Capacitive sensing input 1.
	C12IN1-	AN	—	Comparator C1 or C2 negative input.
	$\overline{SS2}$	ST	—	Slave Select input 2.
RA2/AN2/CPS2/C12IN2-/ C12IN+/VREF-/DACOUT	RA2	TTL	CMOS	General purpose I/O.
	AN2	AN	—	A/D Channel 2 input.
	CPS2	AN	—	Capacitive sensing input 2.
	C12IN2-	AN	—	Comparator C1 or C2 negative input.
	C12IN+	AN	—	Comparator C1 or C2 positive input.
	VREF-	AN	—	A/D Negative Voltage Reference input.
	DACOUT	—	AN	Voltage Reference output.
RA3/AN3/CPS3/C12IN3-/C1IN+/ VREF+/C1OUT/CCP3(2)/SRQ	RA3	TTL	CMOS	General purpose I/O.
	AN3	AN	—	A/D Channel 3 input.
	CPS3	AN	—	Capacitive sensing input 3.
	C12IN3-	AN	—	Comparator C1 or C2 negative input.
	C1IN+	AN	—	Comparator C1 positive input.
	VREF+	AN	—	A/D Voltage Reference input.
	C1OUT	—	CMOS	Comparator C1 output.
	CCP3	ST	CMOS	Capture/Compare/PWM3.
	SRQ	—	CMOS	SR latch non-inverting output.
RA4/AN4/CPS4/C2OUT/T0CKI/ CCP4(2)/SRNQ	RA4	TTL	CMOS	General purpose I/O.
	AN4	AN	—	A/D Channel 4 input.
	CPS4	AN	—	Capacitive sensing input 4.
	C2OUT	—	CMOS	Comparator C2 output.
	T0CKI	ST	—	Timer0 clock input.
	CCP4	ST	CMOS	Capture/Compare/PWM4.
	SRNQ	—	CMOS	SR latch inverting output.
RA5/$\overline{MCLR}$/VPP/$\overline{SS1}$(1,2)	RA5	TTL	CMOS	General purpose I/O.
	$\overline{MCLR}$	ST	—	Master Clear with internal pull-up.
	VPP	HV	—	Programming voltage.
	$\overline{SS1}$	ST	—	Slave Select input 1.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I^2C™ = Schmitt Trigger input with I^2C levels
HV = High Voltage XTAL = Crystal

Note 1: Pin functions can be moved using the APFCON0 or APFCON1 register.
2: Functions are only available on the PIC16(L)F1827.
3: Default function location.

TABLE 3-6: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 4											
20Ch	WPUA	—	—	WPUA5	—	—	—	—	—	--1- ----	--1- ----
20Dh	WPUB	WPUB7	WPUB6	WPUB5	WPUB4	WPUB3	WPUB2	WPUB1	WPUB0	1111 1111	1111 1111
20Eh	—	Unimplemented								—	—
20Fh	—	Unimplemented								—	—
210h	—	Unimplemented								—	—
211h	SSP1BUF	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
212h	SSP1ADD	ADD7	ADD6	ADD5	ADD4	ADD3	ADD2	ADD1	ADD0	0000 0000	0000 0000
213h	SSP1MSK	MSK7	MSK6	MSK5	MSK4	MSK3	MSK2	MSK1	MSK0	1111 1111	1111 1111
214h	SSP1STAT	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	0000 0000	0000 0000
215h	SSP1CON1	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
216h	SSP1CON2	GCEN	ACKSTAT	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	0000 0000	0000 0000
217h	SSP1CON3	ACKTIM	PCIE	SCIE	BOEN	SDAHT	SBCDE	AHEN	DHEN	0000 0000	0000 0000
218h	—	Unimplemented								—	—
219h	SSP2BUF(1)	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
21Ah	SSP2ADD(1)	ADD7	ADD6	ADD5	ADD4	ADD3	ADD2	ADD1	ADD0	0000 0000	0000 0000
21Bh	SSP2MSK(1)	MSK7	MSK6	MSK5	MSK4	MSK3	MSK2	MSK1	MSK0	1111 1111	1111 1111
21Ch	SSP2STAT(1)	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	0000 0000	0000 0000
21Dh	SSP2CON1(1)	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
21Eh	SSP2CON2(1)	GCEN	ACKSTAT	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	0000 0000	0000 0000
21Fh	SSP2CON3(1)	ACKTIM	PCIE	SCIE	BOEN	SDAHT	SBCDE	AHEN	DHEN	0000 0000	0000 0000
Bank 5											
28Ch	—	Unimplemented								—	—
28Dh	—	Unimplemented								—	—
28Eh	—	Unimplemented								—	—
28Fh	—	Unimplemented								—	—
290h	—	Unimplemented								—	—
291h	CCPR1L	Capture/Compare/PWM Register 1 (LSB)								xxxx xxxx	uuuu uuuu
292h	CCPR1H	Capture/Compare/PWM Register 1 (MSB)								xxxx xxxx	uuuu uuuu
293h	CCP1CON	P1M1	P1M0	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	0000 0000	0000 0000
294h	PWM1CON	P1RSEN	P1DC6	P1DC5	P1DC4	P1DC3	P1DC2	P1DC1	P1DC0	0000 0000	0000 0000
295h	CCP1AS	CCP1ASE	CCP1AS2	CCP1AS1	CCP1AS0	PSS1AC1	PSS1AC0	PSS1BD1	PSS1BD0	0000 0000	0000 0000
296h	PSTR1CON	—	—	—	STR1SYNC	STR1D	STR1C	STR1B	STR1A	---0 0001	---0 0001
297h	—	Unimplemented								—	—
298h	CCPR2L(1)	Capture/Compare/PWM Register 2 (LSB)								xxxx xxxx	uuuu uuuu
299h	CCPR2H(1)	Capture/Compare/PWM Register 2 (MSB)								xxxx xxxx	uuuu uuuu
29Ah	CCP2CON(1)	P2M1	P2M0	DC2B1	DC2B0	CCP2M3	CCP2M2	CCP2M1	CCP2M0	0000 0000	0000 0000
29Bh	PWM2CON(1)	P2RSEN	P2DC6	P2DC5	P2DC4	P2DC3	P2DC2	P2DC1	P2DC0	0000 0000	0000 0000
29Ch	CCP2AS(1)	CCP2ASE	CCP2AS2	CCP2AS1	CCP2AS0	PSS2AC1	PSS2AC0	PSS2BD1	PSS2BD0	0000 0000	0000 0000
29Dh	PSTR2CON(1)	—	—	—	STR2SYNC	STR2D	STR2C	STR2B	STR2A	---0 0001	---0 0001
29Eh	CCPTMRS(1)	C4TSEL1	C4TSEL0	C3TSEL1	C3TSEL0	C2TSEL1	C2TSEL0	C1TSEL1	C1TSEL0	0000 0000	0000 0000
29Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, r = reserved.
Shaded locations are unimplemented, read as '0'.

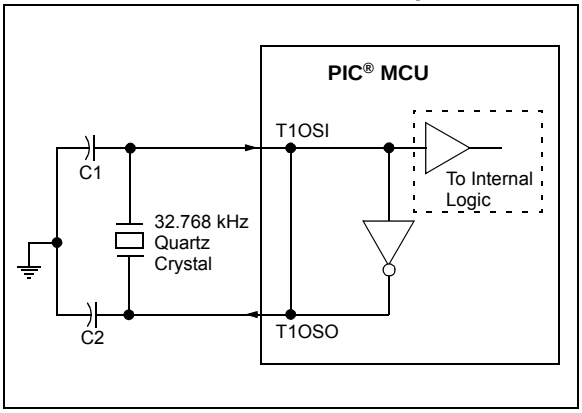
Note 1: PIC16(L)F1827 only.

5.2.1.5 TIMER1 Oscillator

The Timer1 Oscillator is a separate crystal oscillator that is associated with the Timer1 peripheral. It is optimized for timekeeping operations with a 32.768 kHz crystal connected between the T1OSO and T1OSI device pins.

The Timer1 Oscillator can be used as an alternate system clock source and can be selected during run-time using clock switching. Refer to **Section 5.3 "Clock Switching"** for more information.

FIGURE 5-5: QUARTZ CRYSTAL OPERATION (TIMER1 OSCILLATOR)



Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.

2: Always verify oscillator performance over the VDD and temperature range that is expected for the application.

3: For oscillator design assistance, reference the following Microchip Applications Notes:

- AN826, "*Crystal Oscillator Basics and Crystal Selection for rfPIC® and PIC® Devices*" (DS00826)
- AN849, "*Basic PIC® Oscillator Design*" (DS00849)
- AN943, "*Practical PIC® Oscillator Analysis and Design*" (DS00943)
- AN949, "*Making Your Oscillator Work*" (DS00949)
- TB097, "*Interfacing a Micro Crystal MS1V-T1K 32.768 kHz Tuning Fork Crystal to a PIC16F690/SS*" (DS91097)
- AN1288, "*Design Practices for Low-Power External Oscillators*" (DS01288)

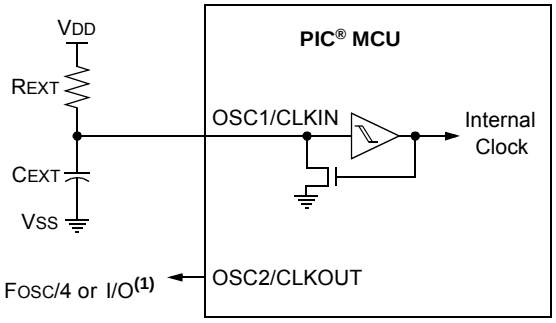
5.2.1.6 External RC Mode

The external Resistor-Capacitor (RC) modes support the use of an external RC circuit. This allows the designer maximum flexibility in frequency choice while keeping costs to a minimum when clock accuracy is not required.

The RC circuit connects to OSC1. OSC2/CLKOUT is available for general purpose I/O or CLKOUT. The function of the OSC2/CLKOUT pin is determined by the state of the $\overline{\text{CLKOUTEN}}$ bit in Configuration Word 1.

Figure 5-6 shows the external RC mode connections.

FIGURE 5-6: EXTERNAL RC MODES



Recommended values: 10 kΩ ≤ REXT ≤ 100 kΩ, <3V
3 kΩ ≤ REXT ≤ 100 kΩ, 3-5V
CEXT > 20 pF, 2-5V

Note 1: Output depends upon $\overline{\text{CLKOUTEN}}$ bit of the Configuration Word 1.

The RC oscillator frequency is a function of the supply voltage, the resistor (REXT) and capacitor (CEXT) values and the operating temperature. Other factors affecting the oscillator frequency are:

- threshold voltage variation
- component tolerances
- packaging variations in capacitance

The user also needs to take into account variation due to tolerance of external RC components used.

7.10 Determining the Cause of a Reset

Upon any Reset, multiple bits in the STATUS and PCON register are updated to indicate the cause of the Reset. Table 7-3 and Table 7-4 show the Reset conditions of these registers.

TABLE 7-3: RESET STATUS BITS AND THEIR SIGNIFICANCE

STKOVF	STKUNF	$\overline{\text{RMCLR}}$	$\overline{\text{RI}}$	$\overline{\text{POR}}$	$\overline{\text{BOR}}$	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Condition
0	0	1	1	0	x	1	1	Power-on Reset
0	0	1	1	0	x	0	x	Illegal, $\overline{\text{TO}}$ is set on $\overline{\text{POR}}$
0	0	1	1	0	x	x	0	Illegal, $\overline{\text{PD}}$ is set on $\overline{\text{POR}}$
0	0	1	1	u	0	1	1	Brown-out Reset
u	u	u	u	u	u	0	u	WDT Reset
u	u	u	u	u	u	0	0	WDT Wake-up from Sleep
u	u	u	u	u	u	1	0	Interrupt Wake-up from Sleep
u	u	0	u	u	u	u	u	$\overline{\text{MCLR}}$ Reset during normal operation
u	u	0	u	u	u	1	0	$\overline{\text{MCLR}}$ Reset during Sleep
u	u	u	0	u	u	u	u	RESET Instruction Executed
1	u	u	u	u	u	u	u	Stack Overflow Reset (STVREN = 1)
u	1	u	u	u	u	u	u	Stack Underflow Reset (STVREN = 1)

TABLE 7-4: RESET CONDITION FOR SPECIAL REGISTERS(2)

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	0000h	---1 1000	00-- 110x
$\overline{\text{MCLR}}$ Reset during normal operation	0000h	---u uuuu	uu-- 0uuu
$\overline{\text{MCLR}}$ Reset during Sleep	0000h	---1 0uuu	uu-- 0uuu
WDT Reset	0000h	---0 uuuu	uu-- uuuu
WDT Wake-up from Sleep	PC + 1	---0 0uuu	uu-- uuuu
Brown-out Reset	0000h	---1 1uuu	00-- 11u0
Interrupt Wake-up from Sleep	PC + 1(1)	---1 0uuu	uu-- uuuu
RESET Instruction Executed	0000h	---u uuuu	uu-- u0uu
Stack Overflow Reset (STVREN = 1)	0000h	---u uuuu	1u-- uuuu
Stack Underflow Reset (STVREN = 1)	0000h	---u uuuu	u1-- uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0'.

Note 1: When the wake-up is due to an interrupt and Global Enable bit (GIE) is set, the return address is pushed on the stack and PC is loaded with the interrupt vector (0004h) after execution of PC + 1.

2: If a Status bit is not implemented, that bit will be read as '0'.

8.0 INTERRUPTS

The interrupt feature allows certain events to preempt normal program flow. Firmware is used to determine the source of the interrupt and act accordingly. Some interrupts can be configured to wake the MCU from Sleep mode.

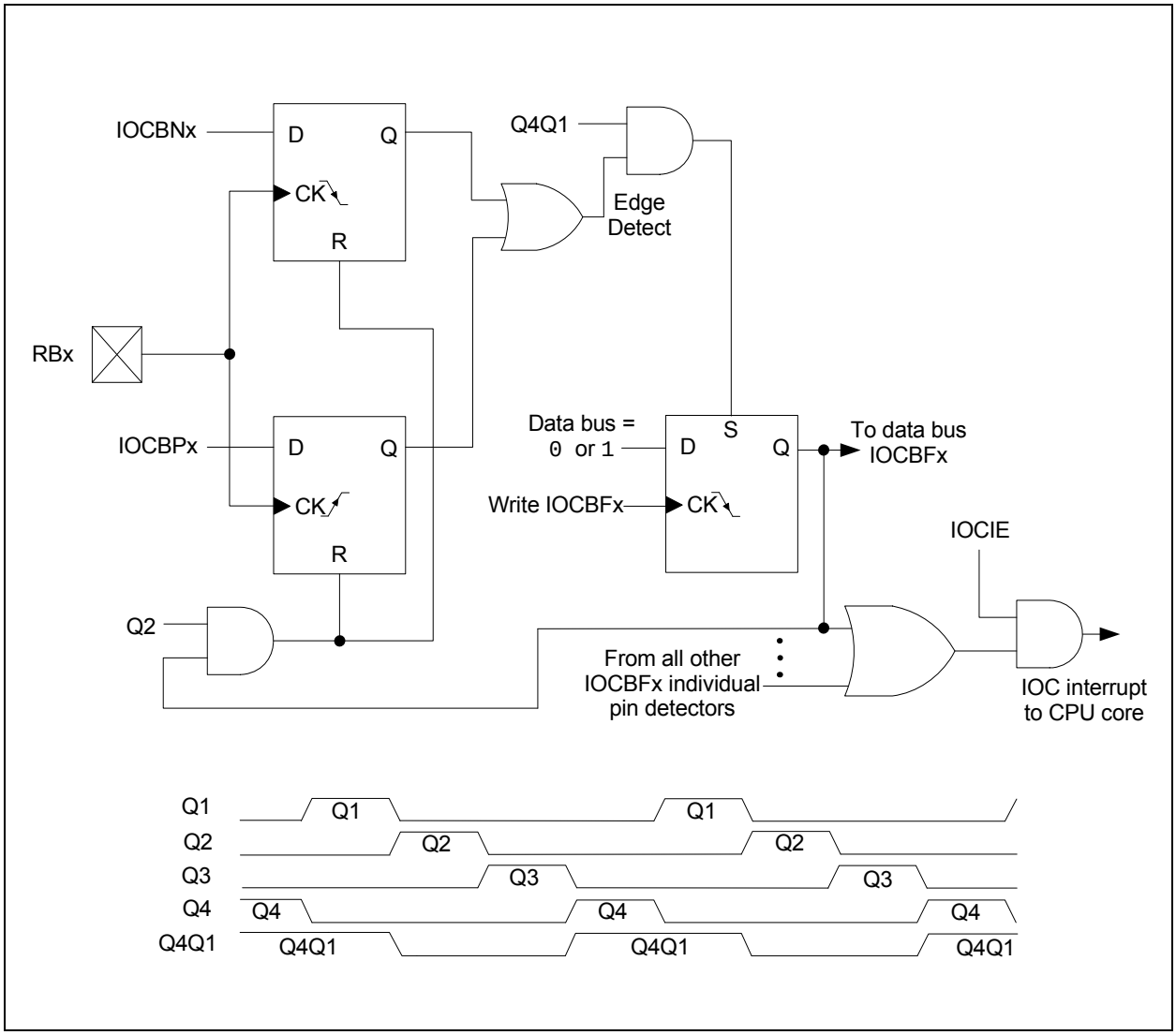
This chapter contains the following information for Interrupts:

- Operation
- Interrupt Latency
- Interrupts During Sleep
- INT Pin
- Automatic Context Saving

Many peripherals produce Interrupts. Refer to the corresponding chapters for details.

A block diagram of the interrupt logic is shown in Figure 8-1.

FIGURE 8-1: INTERRUPT LOGIC



8.6.5 PIE4 REGISTER(1)

The PIE4 register contains the interrupt enable bits, as shown in Register 8-5.

Note 1: The PIE4 register is available only on the PIC16(L)F1827 device.

2: Bit PEIE of the INTCON register must be set to enable any peripheral interrupt.

REGISTER 8-5: PIE4: PERIPHERAL INTERRUPT ENABLE REGISTER 4(1)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0/0	R/W-0/0
—	—	—	—	—	—	BCL2IE	SSP2IE
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-2 **Unimplemented:** Read as ‘0’

bit 1 **BCL2IE:** MSSP2 Bus Collision Interrupt Enable bit
1 = Enables the MSSP2 Bus Collision Interrupt
0 = Disables the MSSP2 Bus Collision Interrupt

bit 0 **SSP2IE:** Master Synchronous Serial Port 2 (MSSP2) Interrupt Enable bit
1 = Enables the MSSP2 interrupt
0 = Disables the MSSP2 interrupt

Note 1: This register is only available on PIC16(L)F1827.

9.0 POWER-DOWN MODE (SLEEP)

The Power-Down mode is entered by executing a SLEEP instruction.

Upon entering Sleep mode, the following conditions exist:

1. WDT will be cleared but keeps running, if enabled for operation during Sleep.
2. $\overline{PD}$ bit of the STATUS register is cleared.
3. $\overline{TO}$ bit of the STATUS register is set.
4. CPU clock is disabled.
5. 31 kHz LFINTOSC is unaffected and peripherals that operate from it may continue operation in Sleep.
6. Timer1 oscillator is unaffected and peripherals that operate from it may continue operation in Sleep.
7. ADC is unaffected, if the dedicated FRC clock is selected.
8. Capacitive Sensing oscillator is unaffected.
9. I/O ports maintain the status they had before SLEEP was executed (driving high, low or high-impedance).
10. Resets other than WDT are not affected by Sleep mode.

Refer to individual chapters for more details on peripheral operation during Sleep.

To minimize current consumption, the following conditions should be considered:

- I/O pins should not be floating
- External circuitry sinking current from I/O pins
- Internal circuitry sourcing current from I/O pins
- Current draw from pins with internal weak pull-ups
- Modules using 31 kHz LFINTOSC
- Modules using Timer1 oscillator

I/O pins that are high-impedance inputs should be pulled to V_{DD} or V_{SS} externally to avoid switching currents caused by floating inputs.

Examples of internal circuitry that might be sourcing current include modules such as the DAC and FVR modules. See **Section 17.0 "Digital-to-Analog Converter (DAC) Module"** and **Section 14.0 "Fixed Voltage Reference (FVR)"** for more information on these modules.

9.1 Wake-up from Sleep

The device can wake-up from Sleep through one of the following events:

1. External Reset input on $\overline{MCLR}$ pin, if enabled
2. BOR Reset, if enabled
3. POR Reset
4. Watchdog Timer, if enabled
5. Any external interrupt
6. Interrupts by peripherals capable of running during Sleep (see individual peripheral for more information)

The first three events will cause a device Reset. The last three events are considered a continuation of program execution. To determine whether a device Reset or wake-up event occurred, refer to **Section 7.10 "Determining the Cause of a Reset"**.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is prefetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be enabled. Wake-up will occur regardless of the state of the GIE bit. If the GIE bit is disabled, the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is enabled, the device executes the instruction after the SLEEP instruction, the device will then call the Interrupt Service Routine. In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

11.3.2 ERASING FLASH PROGRAM MEMORY

While executing code, program memory can only be erased by rows. To erase a row:

1. Load the EEADRH:EEADRL register pair with the address of new row to be erased.
2. Clear the CFGS bit of the EECON1 register.
3. Set the EEPGD, FREE, and WREN bits of the EECON1 register.
4. Write 55h, then AAh, to EECON2 (Flash programming unlock sequence).
5. Set control bit WR of the EECON1 register to begin the erase operation.
6. Poll the FREE bit in the EECON1 register to determine when the row erase has completed.

See Example 11-4.

After the "BSF EECON1,WR" instruction, the processor requires two cycles to set up the erase operation. The user must place two NOP instructions after the WR bit is set. The processor will halt internal operations for the typical 2 ms erase time. This is not Sleep mode as the clocks and peripherals will continue to run. After the erase cycle, the processor will resume operation with the third instruction after the EECON1 write instruction.

11.3.3 WRITING TO FLASH PROGRAM MEMORY

Program memory is programmed using the following steps:

1. Load the starting address of the word(s) to be programmed.
2. Load the write latches with data.
3. Initiate a programming operation.
4. Repeat steps 1 through 3 until all data is written.

Before writing to program memory, the word(s) to be written must be erased or previously unwritten. Program memory can only be erased one row at a time. No automatic erase occurs upon the initiation of the write.

Program memory can be written one or more words at a time. The maximum number of words written at one time is equal to the number of write latches. See Figure 11-2 (block writes to program memory with 32 write latches) for more details. The write latches are aligned to the address boundary defined by EEADRL as shown in Table 11-1. Write operations do not cross these boundaries. At the completion of a program memory write operation, the write latches are reset to contain 0x3FFF.

The following steps should be completed to load the write latches and program a block of program memory. These steps are divided into two parts. First, all write latches are loaded with data except for the last program memory location. Then, the last write latch is loaded and the programming sequence is initiated. A special unlock sequence is required to load a write latch with data or initiate a Flash programming operation. This unlock sequence should not be interrupted.

1. Set the EEPGD and WREN bits of the EECON1 register.
2. Clear the CFGS bit of the EECON1 register.
3. Set the LWLO bit of the EECON1 register. When the LWLO bit of the EECON1 register is '1', the write sequence will only load the write latches and will not initiate the write to Flash program memory.
4. Load the EEADRH:EEADRL register pair with the address of the location to be written.
5. Load the EEDATH:EEDATL register pair with the program memory data to be written.
6. Write 55h, then AAh, to EECON2, then set the WR bit of the EECON1 register (Flash programming unlock sequence). The write latch is now loaded.
7. Increment the EEADRH:EEADRL register pair to point to the next location.
8. Repeat steps 5 through 7 until all but the last write latch has been loaded.
9. Clear the LWLO bit of the EECON1 register. When the LWLO bit of the EECON1 register is '0', the write sequence will initiate the write to Flash program memory.
10. Load the EEDATH:EEDATL register pair with the program memory data to be written.
11. Write 55h, then AAh, to EECON2, then set the WR bit of the EECON1 register (Flash programming unlock sequence). The entire latch block is now written to Flash program memory.

It is not necessary to load the entire write latch block with user program data. However, the entire write latch block will be written to program memory.

An example of the complete write sequence for eight words is shown in Example 11-5. The initial address is loaded into the EEADRH:EEADRL register pair; the eight words of data are loaded using indirect addressing.

REGISTER 11-4: EEADRH: EEPROM ADDRESS HIGH BYTE REGISTER

U-1	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—	EEADR<14:8>						
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **Unimplemented:** Read as ‘1’

bit 6-0 **EEADR<14:8>**: Specifies the Most Significant bits for program memory address or EEPROM address

TABLE 12-6: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELB	ANSB7	ANSB6	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	—	128
LATB	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	127
OPTION_REG	$\overline{\text{WPUEN}}$	INTEDG	TMR0CS	TMR0SE	PSA	PS2	PS1	PS0	176
PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	127
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	127
WPUB	WPUB7	WPUB6	WPUB5	WPUB4	WPUB3	WPUB2	WPUB1	WPUB0	128

Legend: — = unimplemented locations read as '0'. Shaded cells are not used by PORTB.

13.0 INTERRUPT-ON-CHANGE

The PORTB pins can be configured to operate as Interrupt-On-Change (IOC) pins. An interrupt can be generated by detecting a signal that has either a rising edge or a falling edge. Any individual PORTB pin can be configured to generate an interrupt. The interrupt-on-change module has the following features:

- Interrupt-on-Change enable (Master Switch)
- Individual pin configuration
- Rising and falling edge detection
- Individual pin interrupt flags

Figure 13-1 is a block diagram of the IOC module.

13.1 Enabling the Module

To allow individual port pins to generate an interrupt, the IOCIE bit of the INTCON register must be set. If the IOCIE bit is disabled, the edge detection on the pin will still occur, but an interrupt will not be generated.

13.2 Individual Pin Configuration

For each port pin, a rising edge detector and a falling edge detector are present. To enable a pin to detect a rising edge, the associated IOCBPx bit of the IOCBP register is set. To enable a pin to detect a falling edge, the associated IOCBNx bit of the IOCBN register is set.

A pin can be configured to detect rising and falling edges simultaneously by setting both the IOCBPx bit and the IOCBNx bit of the IOCBP and IOCBN registers, respectively.

13.3 Interrupt Flags

The IOCBFx bits located in the IOCBF register are status flags that correspond to the Interrupt-on-change pins of the port. If an expected edge is detected on an appropriately enabled pin, then the status flag for that pin will be set, and an interrupt will be generated if the IOCIE bit is set. The IOCIF bit of the INTCON register reflects the status of all IOCBFx bits.

13.4 Clearing Interrupt Flags

The individual status flags, (IOCBFx bits), can be cleared by resetting them to zero. If another edge is detected during this clearing operation, the associated status flag will be set at the end of the sequence, regardless of the value actually being written.

In order to ensure that no detected edge is lost while clearing flags, only AND operations masking out known changed bits should be performed. The following sequence is an example of what should be performed.

EXAMPLE 13-1:

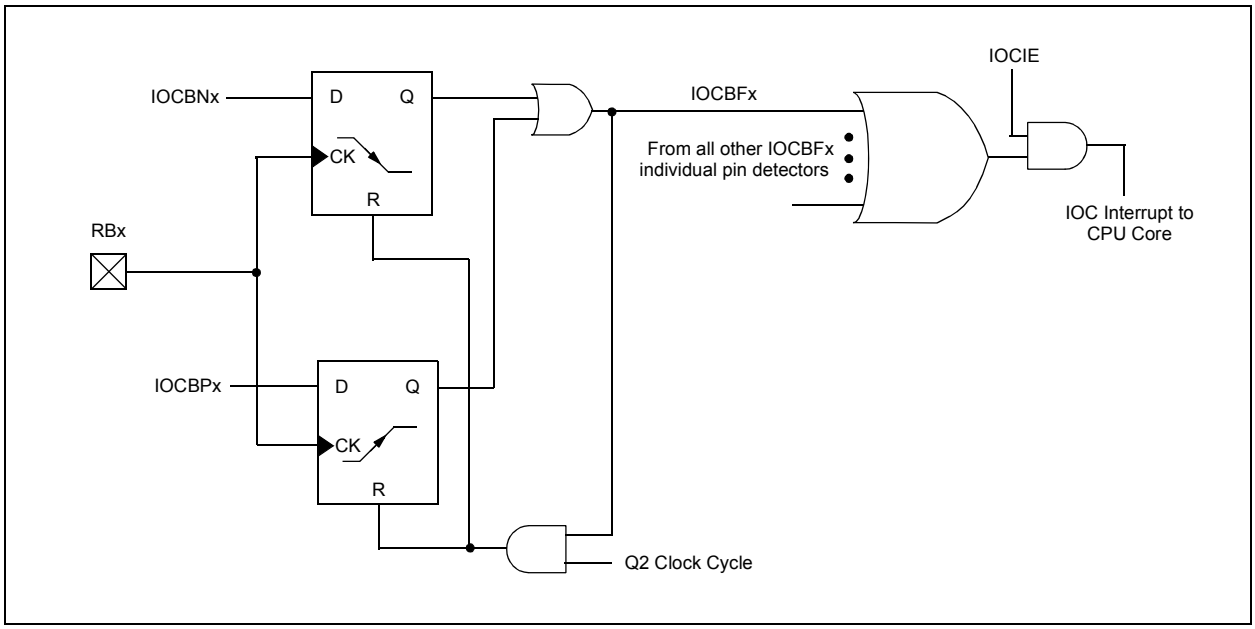
```
MOVLW  0xff
XORWF  IOCBF, W
ANDWF  IOCBF, F
```

13.5 Operation in Sleep

The interrupt-on-change interrupt sequence will wake the device from Sleep mode, if the IOCIE bit is set.

If an edge is detected while in Sleep mode, the IOCBF register will be updated prior to the first instruction executed out of Sleep.

FIGURE 13-1: INTERRUPT-ON-CHANGE BLOCK DIAGRAM



REGISTER 16-3: ADRESH: ADC RESULT REGISTER HIGH (ADRESH) ADFM = 0

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
ADRES<9:2>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **ADRES<9:2>**: ADC Result Register bits
Upper 8 bits of 10-bit conversion result

REGISTER 16-4: ADRESL: ADC RESULT REGISTER LOW (ADRESL) ADFM = 0

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
ADRES<1:0>		—	—	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **ADRES<1:0>**: ADC Result Register bits
Lower 2 bits of 10-bit conversion result

bit 5-0 **Reserved**: Do not use.

19.0 COMPARATOR MODULE

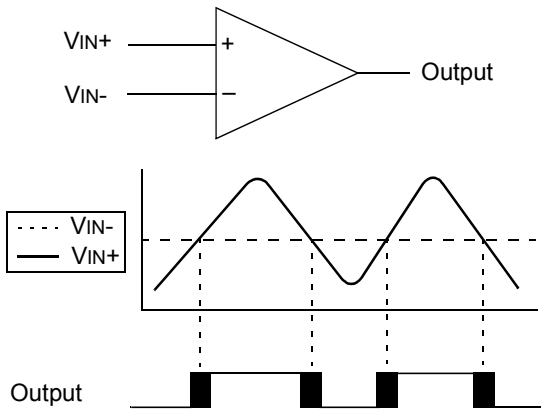
Comparators are used to interface analog circuits to a digital circuit by comparing two analog voltages and providing a digital indication of their relative magnitudes. Comparators are very useful mixed signal building blocks because they provide analog functionality independent of program execution. The analog comparator module includes the following features:

- Independent comparator control
- Programmable input selection
- Comparator output is available internally/externally
- Programmable output polarity
- Interrupt-on-change
- Wake-up from Sleep
- Programmable Speed/Power optimization
- PWM shutdown
- Programmable and fixed voltage reference

19.1 Comparator Overview

A single comparator is shown in Figure 19-1 along with the relationship between the analog input levels and the digital output. When the analog voltage at VIN+ is less than the analog voltage at VIN-, the output of the comparator is a digital low level. When the analog voltage at VIN+ is greater than the analog voltage at VIN-, the output of the comparator is a digital high level.

FIGURE 19-1: SINGLE COMPARATOR



Note: The black areas of the output of the comparator represents the uncertainty due to input offsets and response time.

19.3 Comparator Hysteresis

A selectable amount of separation voltage can be added to the input pins of each comparator to provide a hysteresis function to the overall operation. Hysteresis is enabled by setting the CxHYS bit of the CMxCON0 register.

See **Section 29.0 "Electrical Specifications"** for more information.

19.4 Timer1 Gate Operation

The output resulting from a comparator operation can be used as a source for gate control of Timer1. See **Section 21.6 "Timer1 Gate"** for more information. This feature is useful for timing the duration or interval of an analog event.

It is recommended that the comparator output be synchronized to Timer1. This ensures that Timer1 does not increment while a change in the comparator is occurring.

19.4.1 COMPARATOR OUTPUT SYNCHRONIZATION

The output from either comparator, C1 or C2, can be synchronized with Timer1 by setting the CxSYNC bit of the CMxCON0 register.

Once enabled, the comparator output is latched on the falling edge of the Timer1 source clock. If a prescaler is used with Timer1, the comparator output is latched after the prescaling function. To prevent a race condition, the comparator output is latched on the falling edge of the Timer1 clock source and Timer1 increments on the rising edge of its clock source. See the Comparator Block Diagrams (Figure 19-2 and Figure 19-3) and the Timer1 Block Diagram (Figure 21-1) for more information.

19.5 Comparator Interrupt

An interrupt can be generated upon a change in the output value of the comparator for each comparator, a rising edge detector and a Falling edge detector are present.

When either edge detector is triggered and its associated enable bit is set (CxINTP and/or CxINTN bits of the CMxCON1 register), the Corresponding Interrupt Flag bit (CxIF bit of the PIR2 register) will be set.

To enable the interrupt, you must set the following bits:

- CxON, CxPOL and CxSP bits of the CMxCON0 register
- CxIE bit of the PIE2 register
- CxINTP bit of the CMxCON1 register (for a rising edge detection)
- CxINTN bit of the CMxCON1 register (for a falling edge detection)
- PEIE and GIE bits of the INTCON register

The associated interrupt flag bit, CxIF bit of the PIR2 register, must be cleared in software. If another edge is detected while this flag is being cleared, the flag will still be set at the end of the sequence.

Note:	Although a comparator is disabled, an interrupt can be generated by changing the output polarity with the CxPOL bit of the CMxCON0 register, or by switching the comparator on or off with the CxON bit of the CMxCON0 register.

19.6 Comparator Positive Input Selection

Configuring the CxPCH<1:0> bits of the CMxCON1 register directs an internal voltage reference or an analog pin to the non-inverting input of the comparator:

- C1IN+ or C2IN+ analog pin
- DAC
- FVR (Fixed Voltage Reference)
- VSS (Ground)

See **Section 14.0 "Fixed Voltage Reference (FVR)"** for more information on the Fixed Voltage Reference module.

See **Section 17.0 "Digital-to-Analog Converter (DAC) Module"** for more information on the DAC input signal.

Any time the comparator is disabled (CxON = 0), all comparator inputs are disabled.

21.12 Timer1 Gate Control Register

The Timer1 Gate Control register (T1GCON), shown in Register 21-2, is used to control Timer1 gate.

REGISTER 21-2: T1GCON: TIMER1 GATE CONTROL REGISTER

R/W-0/u	R/W-0/u	R/W-0/u	R/W-0/u	R/W/HC-0/u	R-x/x	R/W-0/u	R/W-0/u
TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/$\overline{\text{DONE}}$	T1GVAL	T1GSS<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	HC = Bit is cleared by hardware

bit 7 **TMR1GE:** Timer1 Gate Enable bit

If TMR1ON = 0:
This bit is ignored
If TMR1ON = 1:
1 = Timer1 counting is controlled by the Timer1 gate function
0 = Timer1 counts regardless of Timer1 gate function

bit 6 **T1GPOL:** Timer1 Gate Polarity bit

1 = Timer1 gate is active-high (Timer1 counts when gate is high)
0 = Timer1 gate is active-low (Timer1 counts when gate is low)

bit 5 **T1GTM:** Timer1 Gate Toggle Mode bit

1 = Timer1 Gate Toggle mode is enabled
0 = Timer1 Gate Toggle mode is disabled and toggle flip-flop is cleared
Timer1 gate flip-flop toggles on every rising edge.

bit 4 **T1GSPM:** Timer1 Gate Single-Pulse Mode bit

1 = Timer1 gate Single-Pulse mode is enabled and is controlling Timer1 gate
0 = Timer1 gate Single-Pulse mode is disabled

bit 3 **T1GGO/$\overline{\text{DONE}}$:** Timer1 Gate Single-Pulse Acquisition Status bit

1 = Timer1 gate single-pulse acquisition is ready, waiting for an edge
0 = Timer1 gate single-pulse acquisition has completed or has not been started

bit 2 **T1GVAL:** Timer1 Gate Current State bit

Indicates the current state of the Timer1 gate that could be provided to TMR1H:TMR1L.
Unaffected by Timer1 Gate Enable (TMR1GE).

bit 1-0 **T1GSS<1:0>:** Timer1 Gate Source Select bits

00 = Timer1 gate pin
01 = Timer0 overflow output
10 = Comparator 1 optionally synchronized output (SYNCC1OUT)
11 = Comparator 2 optionally synchronized output (SYNCC2OUT)

REGISTER 25-5: SSPxMSK: SSPx MASK REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
MSK<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-1 **MSK<7:1>:** Mask bits
1 = The received address bit n is compared to SSPxADD<n> to detect I^2C address match
0 = The received address bit n is not used to detect I^2C address match

bit 0 **MSK<0>:** Mask bit for I^2C Slave mode, 10-bit Address
I^2C Slave mode, 10-bit address (SSPxM<3:0> = 0111 or 1111):
1 = The received address bit 0 is compared to SSPxADD<0> to detect I^2C address match
0 = The received address bit 0 is not used to detect I^2C address match
I^2C Slave mode, 7-bit address, the bit is ignored

REGISTER 25-6: SSPxADD: MSSPx ADDRESS AND BAUD RATE REGISTER (I^2C MODE)

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
ADD<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

Master mode:

bit 7-0 **ADD<7:0>:** Baud Rate Clock Divider bits
SCLx pin clock period = ((ADD<7:0> + 1) *4)/FOSC

10-Bit Slave mode — Most Significant Address byte:

bit 7-3 **Not used:** Unused for Most Significant Address byte. Bit state of this register is a "don't care". Bit pattern sent by master is fixed by I^2C specification and must be equal to '11110'. However, those bits are compared by hardware and are not affected by the value in this register.

bit 2-1 **ADD<2:1>:** Two Most Significant bits of 10-bit address

bit 0 **Not used:** Unused in this mode. Bit state is a "don't care".

10-Bit Slave mode — Least Significant Address byte:

bit 7-0 **ADD<7:0>:** Eight Least Significant bits of 10-bit address

7-Bit Slave mode:

bit 7-1 **ADD<7:1>:** 7-bit address

bit 0 **Not used:** Unused in this mode. Bit state is a "don't care".

26.2 Clock Accuracy with Asynchronous Operation

The factory calibrates the internal oscillator block output (INTOSC). However, the INTOSC frequency may drift as VDD or temperature changes, and this directly affects the asynchronous baud rate. Two methods may be used to adjust the baud rate clock, but both require a reference clock source of some kind.

The first (preferred) method uses the OSCTUNE register to adjust the INTOSC output. Adjusting the value in the OSCTUNE register allows for fine resolution changes to the system clock source. See **Section 5.2.2 "Internal Clock Sources"** for more information.

The other method adjusts the value in the Baud Rate Generator. This can be done automatically with the Auto-Baud Detect feature (see **Section 26.3.1 "Auto-Baud Detect"**). There may not be fine enough resolution when adjusting the Baud Rate Generator to compensate for a gradual change in the peripheral clock frequency.

REGISTER 26-1: TXSTA: TRANSMIT STATUS AND CONTROL REGISTER

R/W-/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R-1/1	R/W-0/0
CSRC	TX9	TXEN(1)	SYNC	SENDB	BRGH	TRMT	TX9D
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **CSRC:** Clock Source Select bit
Asynchronous mode:
Don't care
Synchronous mode:
1 = Master mode (clock generated internally from BRG)
0 = Slave mode (clock from external source)

bit 6 **TX9:** 9-bit Transmit Enable bit
1 = Selects 9-bit transmission
0 = Selects 8-bit transmission

bit 5 **TXEN:** Transmit Enable bit(1)
1 = Transmit enabled
0 = Transmit disabled

bit 4 **SYNC:** EUSART Mode Select bit
1 = Synchronous mode
0 = Asynchronous mode

bit 3 **SENDB:** Send Break Character bit
Asynchronous mode:
1 = Send Sync Break on next transmission (cleared by hardware upon completion)
0 = Sync Break transmission completed
Synchronous mode:
Don't care

bit 2 **BRGH:** High Baud Rate Select bit
Asynchronous mode:
1 = High speed
0 = Low speed
Synchronous mode:
Unused in this mode

bit 1 **TRMT:** Transmit Shift Register Status bit
1 = TSR empty
0 = TSR full

bit 0 **TX9D:** Ninth bit of Transmit Data
Can be address/data bit or a parity bit.

Note 1: SREN/CREN overrides TXEN in Sync mode.

30.3 DC Characteristics: PIC16(L)F1826/27-I/E (Power-Down) (Continued)

PIC16LF1826/27			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
PIC16F1826/27			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	Device Characteristics	Min.	Typ†	Max. +85°C	Max. +125°C	Units	Conditions	
							VDD	Note
	Power-down Base Current (IPD)(2)							
D026A*		—	250	—	—	µA	1.8	A/D Current **(Note 1, Note 3)**, conversion in progress
		—	250	—	—	µA	3.0	
D026A*		—	280	—	—	µA	1.8	A/D Current **(Note 1, Note 3)**, conversion in progress
		—	280	—	—	µA	3.0	
		—	280	—	—	µA	5.0	
D027		—	3.5	6	8	µA	1.8	Cap Sense Low Power Oscillator mode **(Note 1)**
		—	7	10	14	µA	3.0	
D027		—	4.3	36	38	µA	1.8	Cap Sense Low Power Oscillator mode **(Note 1)**
		—	5.8	39	42	µA	3.0	
		—	6.3	42	45	µA	5.0	
D027A		—	4.2	8	10	µA	1.8	Cap Sense Medium Power Oscillator mode **(Note 1)**
		—	6	12	15	µA	3.0	
D027A		—	7.4	38	40	µA	1.8	Cap Sense Medium Power Oscillator mode **(Note 1)**
		—	9.7	42	43	µA	3.0	
		—	10.4	46	48	µA	5.0	
D027B		—	6	10	15	µA	1.8	Cap Sense High Power Oscillator mode **(Note 1)**
		—	10	14	20	µA	3.0	
D027B		—	17	44	50	µA	1.8	Cap Sense High Power Oscillator mode **(Note 1)**
		—	41	68	80	µA	3.0	
		—	50	78	90	µA	5.0	
D028		—	6.9	11	15	µA	1.8	Comparator Current, Low Power mode, one comparator enabled **(Note 1)**
		—	7.0	13	16	µA	3.0	
D028		—	24	45	60	µA	1.8	Comparator Current, Low Power mode, one comparator enabled **(Note 1)**
		—	24.5	60	70	µA	3.0	
		—	25	65	75	µA	5.0	
D028A		—	7.0	12	16	µA	1.8	Comparator Current, Low Power mode, two comparators enabled **(Note 1)**
		—	7.2	14	17	µA	3.0	
D028A		—	24	45	60	µA	1.8	Comparator Current, Low Power mode, two comparators enabled **(Note 1)**
		—	24.5	60	70	µA	3.0	
		—	25	65	75	µA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral current is the sum of the base IDD or IPD and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base IDD or IPD current from this limit. Max values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins set to inputs state and tied to VDD.

3: A/D oscillator source is FRC.

30.3 DC Characteristics: PIC16(L)F1826/27-I/E (Power-Down) (Continued)

PIC16LF1826/27			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
PIC16F1826/27			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	Device Characteristics	Min.	Typ†	Max. +85°C	Max. +125°C	Units	Conditions	
							VDD	Note
	Power-down Base Current (IPD)(2)							
D028B		—	24	32	40	µA	1.8	Comparator Current, High Power mode, one comparator enabled **(Note 1)**
		—	25	35	45	µA	3.0	
D028B		—	36	60	80	µA	1.8	Comparator Current, High Power mode, one comparator enabled **(Note 1)**
		—	37	63	87	µA	3.0	
		—	38	65	90	µA	5.0	
D028C		—	40	80	90	µA	1.8	Comparator Current, High Power mode, two comparators enabled
		—	41	83	95	µA	3.0	
D028C		—	43	86	100	µA	1.8	Comparator Current, High Power mode, two comparators enabled **(Note 1)**
		—	44	90	105	µA	3.0	
		—	45	95	110	µA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

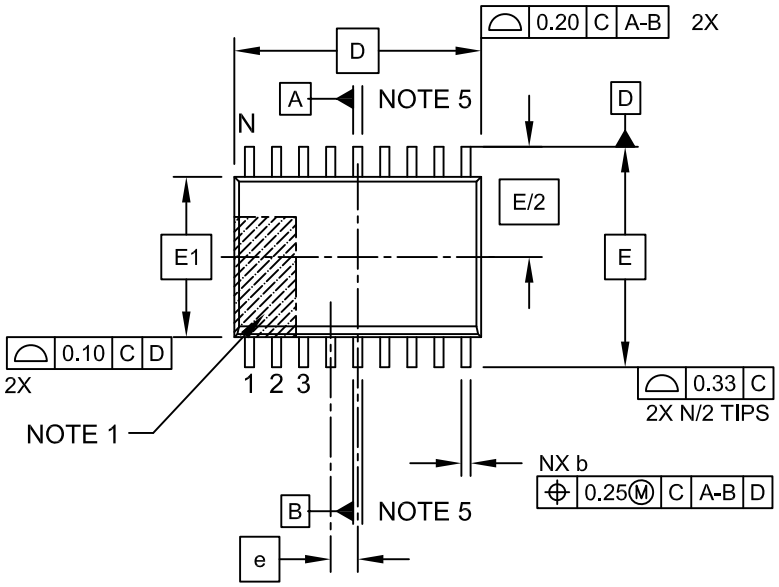
Note 1: The peripheral current is the sum of the base IDD or IPD and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base IDD or IPD current from this limit. Max values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins set to inputs state and tied to VDD.

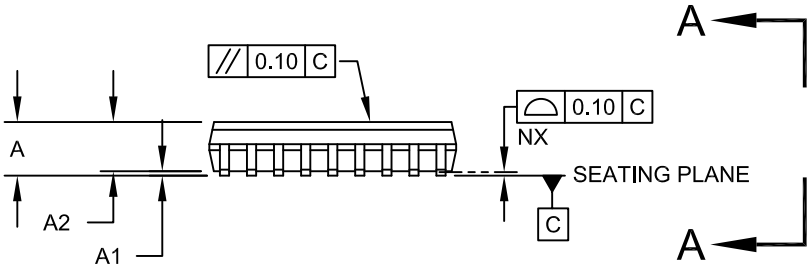
3: A/D oscillator source is FRC.

18-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

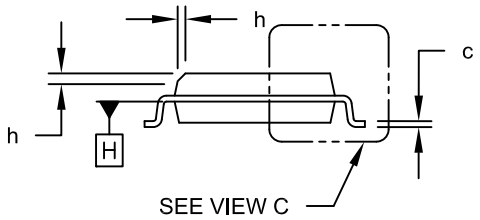
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW



VIEW A-A

Microchip Technology Drawing C04-051C Sheet 1 of 2